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Optimization of bias rail implementations for segmented silicon sensors

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Motivation

Device simulation

- Aluminum bias rails necessary to test segmented silicon sensors
- Testing segmented AC coupled sensors simplified by introducing additional bias rails
- However, depending on the geometry, rails also lead to a certain amount of inefficiency

Efficiency measurement at test beam

- Macropixel sensor (100 \times 1446 μ m²) with aluminum bias rail bump bonded to binary readout chip
- 5.6 GeV positron beam at DESY, Germany
- EUDET-type beam telescope for track reconstruction





- TCAD simulations offer deeper understanding of possible reasons for efficiency loss
- Electric field distribution and charge collection efficiency used to determine and optimize critical parts of the sensor
- **Tool: Sentaurus TCAD (Synopsys)**



Layout

Design study based on macropixel layout with 75 µm spacing between opposing pixels



- Investigation of three bias rail implementations

р р 100 µm

Efficiency analysis

- P-stop implant necessary to isolate single pixels in *n*-in-*p* sensors
- The closer the p-stops the higher the efficiency below the rail
- Common p-stop approach $(d = 0 \ \mu m)$ shows highest efficiency between opposing pixels
- Additional implant below bias rail helps to set up uniform electric field between pixels (bias ring extension)
- Connected implant acts as



Maximum electric field in the bulk

- Sensor with floating implant shows an increased maximum electric field
- Maximum is always located at the interface between p-stop and silicon dioxide
- Closer p-stop rings lead to reduced field strength



 \blacksquare SiO₂

— Al

Conclusion and outlook

Bias rails with connected implant act as additional strips that collect almost all charge generated below them

additional strip which collects charge that is not available for further processing

Design with floating implant reduces inefficiency below the rail

Similar performance as geometry without additional implantation



Floating implant Efficiency 0.95 Collection 28.0 \rightarrow d_{pstop} : 8.0 μ m 08.0 d_{pstop} : 10.0 μ m d_{pstop} : 12.0 μ m - d_{pstop} : 13.0 μ m 0.75 30 10 40 20 *x*i (μm)

Common p-stop between opposing pixels preferable considering charge collection and maximum electric field

Prototypes for further test beam studies expected in February 2018



Common p-stop prototype

www.kit.edu

